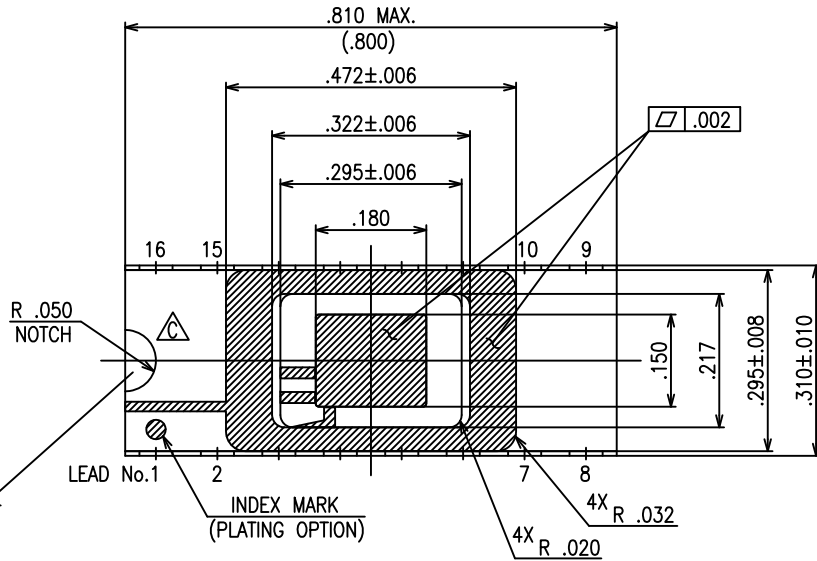
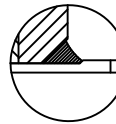
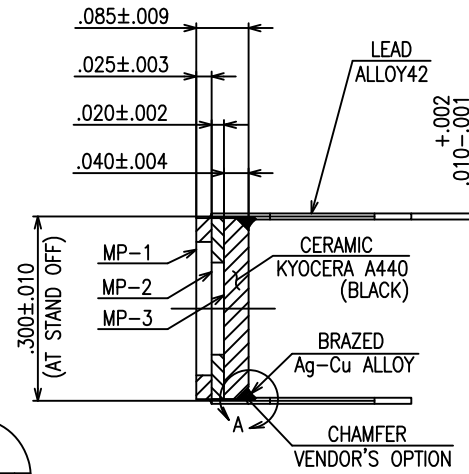
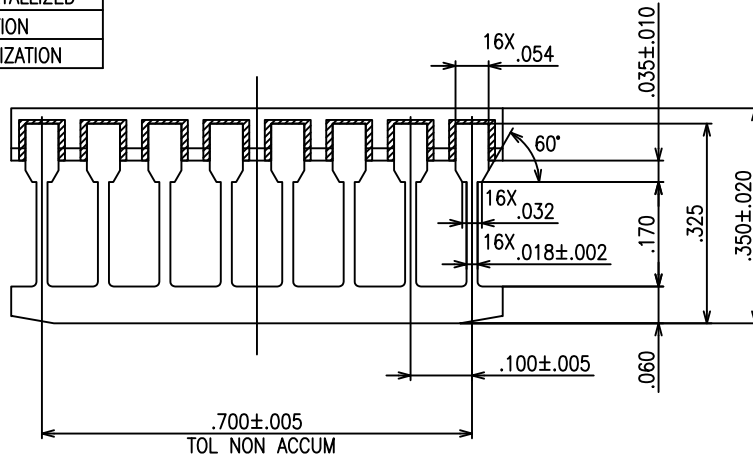


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PART NO.	NOTCH AREA METALLIZED
1	WITH METALLIZATION
2	WITHOUT METALLIZATION



DETAIL-A

NOTES:

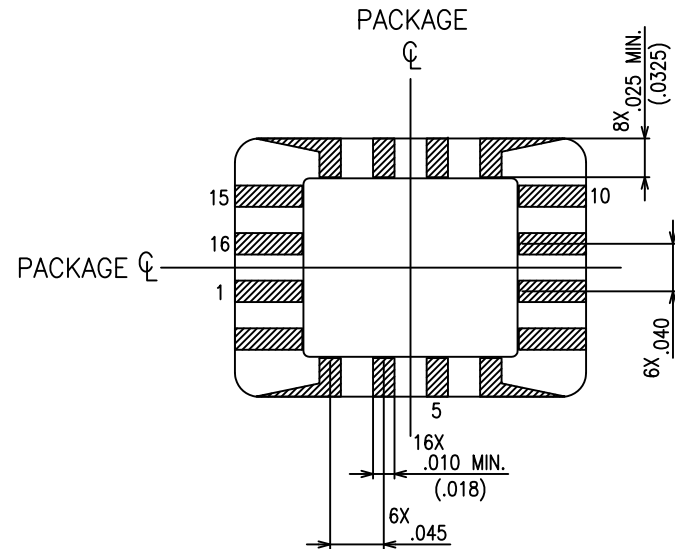
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY LEADS.
5. LEAD RESISTANCE : 0.20 OHM MAX.
6. WIRE BOND PAD CONNECTED TO CORRESPONDED OUTER PAD.
7. MISALIGNMENT OF METALLIZATION PATTERN IN CAVITY SHALL BE ACCEPTED DUE TO LAYER MISALIGNMENT.

SB016G129-2	S=0
	D=0
SB016G129-1	S=0
	D=0

MODIFICATION	DESCRIPTION	DATE	DRAWN	CHECKED	APPROVED	NAME	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
ADDED:SHEET(2/2)					SCALE 5/1	MATERIAL AS INDICATED	THIRD ANGLE PROJECTION				
REDRAWN:CONVERTED CAD DATA.	OCT.22.'98	Y.M	SH.K/S.F	T.A	<b>KYOCERA</b>	KYOCERA CORPORATION KYOTO JAPAN					
CHANGED	DATE	DRAWN	CHECKED	APPROVED							DRAWING NO. KD-S76129-C
											SHEET 1/2



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BONDING PATTERN

MODIFICATION						NAME 16 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN Y.M	CHECKED SH.K/S.F	APPROVED T.A	DATE OCT.22.'98
						SCALE 10/1	MATERIAL				
							THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	<b>KYOCERA</b>	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-S76129-C		SHEET 2/2	

